



17236 U.S.PTO

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:) DIVISIONAL
) PATENT APPLICATION
Inventors: Wei Pan, David R. Evans)
and Sheng Teng Hsu) January 21, 2004
Serial No.: Unknown)
Attorney Docket No.
SLA0861 (SLA0603D)
Filed: Herewith) Parent Application:
Title: INTEGRATED CIRCUIT) Serial No. 10/140,460
STRUCTURE WITH COPPER) Filed: May 6, 2002
INTERCONNECT)
Pending in Group Art
Unit 2818
Examiner: Thao P. Le
Assignee: Sharp Laboratories of) Anticipated Classification:
America, Inc.) Class: 257
Subclass: 565

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**CERTIFICATE OF MAILING BY "EXPRESS MAIL"
UNDER 37 C.F.R. 1.10**

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Victoria Woods

Signature Date: January 21, 2004

DIVISIONAL APPLICATION UNDER 37 C.F.R. §1.53(b)

Mail Stop PATENT APPLICATION
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P.O. Box 1450
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Sir:

The undersigned, attorney-of-record in parent application Serial No. 10/140,460, filed May, 2002, entitled "Ultra Thin Tungsten Metal Films Used as Adhesion Promoter Between Barrier Metals and Copper," hereby requests the filing of a Divisional Application under the provisions of 37 C.F.R. §1.53(b).

Identification of the Parent of the Present Divisional Application:

Serial No.: 10/140,460

Filed: May 6, 2002

Title: Ultra Thin Tungsten Metal Films Used as Adhesion Promoter Between Barrier Metals and Copper

Inventors: Wei Pan, David R. Evans, and Sheng Teng Hsu

Status: Pending

Copy of Present Divisional Application:

Enclosed is a copy of the present divisional application which incorporates the following changes from the as-filed specification and drawings in parent application Serial No. 10/140,460: The titled has been changed, an introductory cross-reference section has been added on page 1, and formal drawings have replaced the as-filed informal drawings. The present divisional application includes the following papers:

- X No. of Pages in Specification: 12 No. of Claims: 21.
- X No. of Sheets of Drawings: 2 Formal: X or Informal: .
- X Copy of the Declaration (signed by all inventors) in parent application Serial No. 10/140,460.
- X Copy of the Power of Attorney in parent application Serial No. 10/140,460.

Parent application Serial No. 10/140,460, filed May 6, 2002, entitled " Ultra Thin Tungsten Metal Films Used as Adhesion Promoter Between Barrier Metals and Copper," is hereby incorporated herein by reference.

Delete the Following Inventor(s) for This Application: None

Amendments:

X Please amend the enclosed specification as follows:

Cancel claims 1-18.

Filing Fee

The Divisional Patent Application filing fee is calculated after cancellation of claims 1-18, as shown below:

	No. Filed	No. Extra	Rate Small Entity/ Other Than Small Entity	
Basic Fee			\$385.00	\$ 770.00
Total Claims <u>3</u>	(20)	= <u>0</u> X	\$ 9.00 \$18.00 =	\$ 00.00
Independent Claims <u>1</u>	(3)	= <u>0</u> X	\$43.00 \$86.00 =	\$ 00.00
First Presentation of Multiple Dependent Claim(s) <u>0</u>			\$145.00 \$290.00 =	\$ 00.00
Total PATENT APPLICATION FILING FEE				\$ 770.00

The total fee associated with this communication is as follows:

Patent application filing fee	\$ 770.00
TOTAL FEE DUE:	\$ 770.00

Method of Payment of Fees

A check in the amount of the TOTAL FEE DUE is enclosed.

Please charge Deposit Account No. 19-1457 in the amount of \$ 770.00.
A duplicate copy of this authorization is enclosed.

The Commissioner is hereby authorized to charge underpayment
of any fees associated with this communication, or
credit any overpayment, to Deposit Account No. 19-1457. A
duplicate copy of this authorization is enclosed.

Customer Number

The Customer Number of the undersigned attorney is:

27518

Correspondence Address

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Date: 1/21/03

Respectfully submitted,

By:

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